

ARK Menu

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Intel® C612 Chipset (Intel® DH82029 PCH)

Specifications

Essentials

Graphics Specifications

Expansion Options

I/O Specifications

Package Specifications

Advanced Technologies

Intel® Platform

Protection Technology

Ordering / sSpecs / Steppings

Specifications

Essentials

Status	Launched
Launch Date	09/08/2014
DMI2	5 GT/s
Embedded Options Available	Yes
Lithography	32 nm
TDP	7 W
Recommended Customer Price	
Supports Overclocking	No

Graphics Specifications

Integrated Graphics †	No
Graphics Output	No
Intel® Clear Video Technology	No
Macrovision* License Required	No

Expansion Options

PCI Support	PCIe
PCI Express Revision	Gen 2
PCI Express Configurations †	x1, x2, x4
Max # of PCI Express Lanes	8

I/O Specifications

USB Revision	3.0 and 2.0
# of USB Ports	14
USB 3.0	6
USB 2.0	8
Total # of SATA Ports	10
Max # of SATA 6.0 Gb/s Ports	10
RAID Configuration	RSTe 4.0
Integrated LAN	1 GbE
Integrated SAS ports	N/A
PCIe* Uplink	N/A

Package Specifications

T _{CASE}	93°C
Package Size	25mm x 25 mm
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) †	Yes
Intel® vPro Technology †	Yes
Intel® ME Firmware Version	9.1
Intel® Remote PC Assist Technology	No
Intel® Quiet System Technology	No
Intel® HD Audio Technology	Yes
Intel® Matrix Storage Technology	No
Intel® Rapid Storage Technology	No
Intel® Rapid Storage Technology enterprise	Yes
Intel® QuickAssist Technology	No
Intel® Node Manager	Yes
Intel® Standard Manageability	Yes
Intel® Rapid Start Technology	Yes

Intel® Platform Protection Technology

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PCN/MDDS Information

SLKM8
938954: MDDS
SLKDD
932728: PCN | MDDS

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Refer to Datasheet for formal definitions of product properties and features.

*Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet J5-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. For more information, visit <http://www.intel.com/content/www/us/en/gaming/overclocking/overclocking-intel-processors.html>

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